

Amendments to the Specification

IN THE TITLE

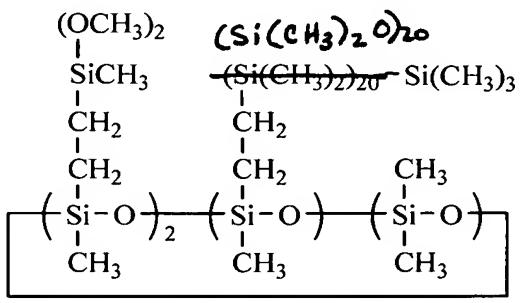
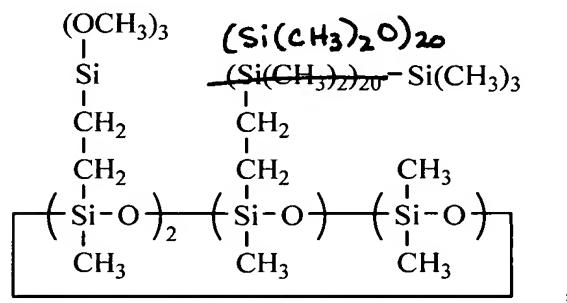
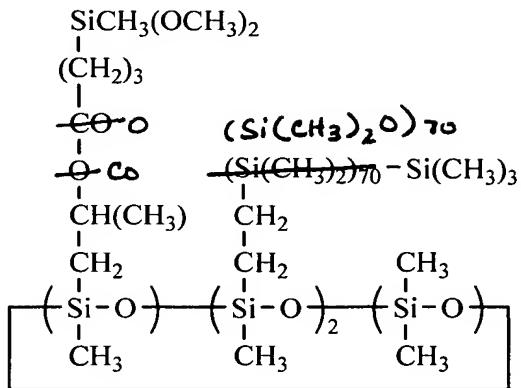
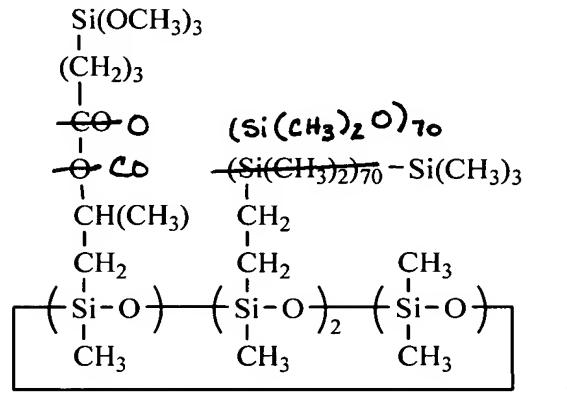
Please change USPTO records to indicate that the title to be used in this application is ---**THERMAL CONDUCTIVE SILICONE COMPOSITION**---, which title coincides with the title appearing in the English translation of the specification.

IN THE WRITTEN DESCRIPTION

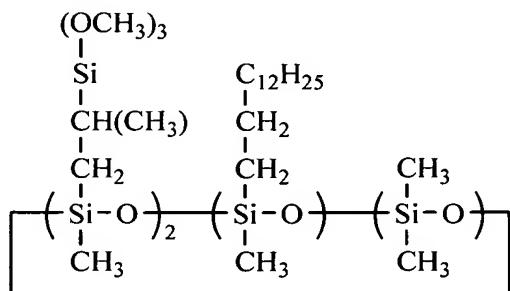
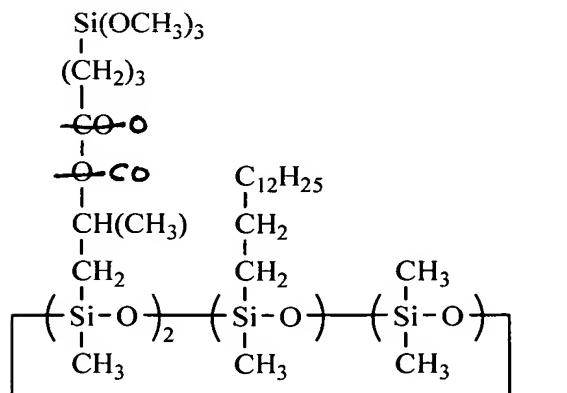
Please replace the paragraph beginning at page 1, line 8, with the following rewritten paragraph:

The heat dissipation of electronic devices, Integrated Circuit (IC) elements and the like is an enormous challenge to the microelectronic industry. Heat conductive greases and thermal conductive sheets have been used to prevent heat accumulation in heating elements of electronic parts typified by power transistors, ICs and CPUs. The advantage of thermal conductive greases is that can be applied to conform to the shape of the electronic parts. However, one key issue with thermal conductive greases is that over time oil bleed out may occur which contaminates other parts/components on the printed circuit. As for thermally conductive sheet, their advantage is that they do not contaminate other parts and is free from the bleeding of oil. However, it is less adhesive than greases and therefore, measures are taken to drop the hardness of the thermal-conductive sheet, thereby improving adhesion (JP-A 1-49959 and JP-B 2623380).

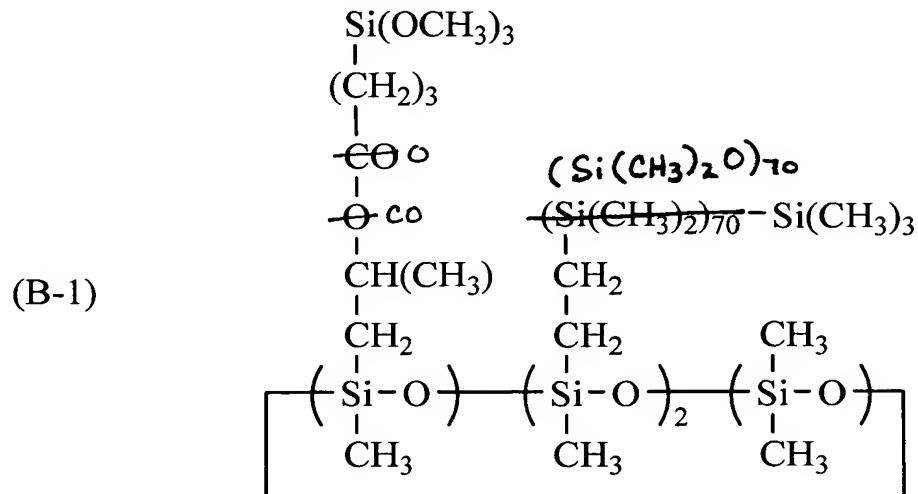
Please replace the formulas beginning at page 7, line 10,
with the following rewritten formulas:



Please replace the formulas beginning at page 8, line 1,
with the following rewritten formulas:



Please replace the formula beginning at page 14, line 17,
with the following rewritten formula:



Please replace the formulas beginning at page 15, line 1,
with the following rewritten formulas:

